

# Ben Stirling

## —Education

### University of California, San Diego

*BS in Computer Engineering*

**GPA: 3.63**

*September 2022 - June 2024*

## —Experience

### Comma.ai

*Pick and Place Operator*

*July 2023 - May 2024*

Operating SMD production with MY300 and MY700. Produced 1000s of consumer electronics products that enable autonomous driving. Helped optimize workflow of pick and place machines and created tooling to help rework processes go smoother and faster. Designed circuit boards to test, writing proper software unit tests.

### Qualcomm Institute

*Makerspace Intern*

*July 2022 - July 2023*

Maintained hundreds of machines, helped hundreds of students.

Skills I learned (and taught): MIG / TIG welding, SMD + THT soldering and reflow, 3D Printing (PLA, PETG, CF, ABS, Resin), Laser Cutters (CO2, Fiber), CNC Machining (mainly exotic hardwoods). Also maintained hundreds of machines, helped hundreds of students.

### DWE.ai

*Chief Financial Officer*

*October 2021 - September 2022*

Performed financial duties, alongside CEO. Met with dozens of customers, networked with VCs and other founders at several events, met and went through EvoNexus interview and onboarding process. Assisted with dozens of sales calls with customers. Helped incorporate and file the first provisional patent.

## —Projects

### Botion

*Notion-based breakout task app, found on the App Store*

### Reverse-engineer Circuits

*2023 SDx Hackathon Qualcomm Winner*

### Inventory System

*Custom inventory management software   Sold 30+ Cards in first 6 months, published BotionNFC on App Store*

### Custom NFC Business Cards

## —Technical Skills

**Strong Programming Languages:** Python, C, C++, Web (HTML+JS+CSS), Swift, SwiftUI, Git, Vim

**Strong Technical Skills:** Computer Aided Design (OnShape, Fusion 360), 3D Printing, PCB Design (KiCAD)